



FR406N

FR406 No-Flo and FR406 Lo-Flo® Specialty Prepreg

Isola offers a FR406N family of no-flow and low-flow prepregs consisting of proprietary resin systems specifically formulated for optimal performance in bonding applications requiring minimal resin flow and consistency in lamination.

FR406 No-Flo and FR406 Lo-Flo® products bring the fabricator specific thermal characteristics appropriate for use in heat sink bonding, die cavity board (direct chip attachment) and multilayer rigid-flex applications.

Product Attributes

Legacy Materials , No / Low Flow Prepreg

Typical Market Applications

Aerospace & Defense

Data Sheet

Tg 170°C

Td 300°C

Dk 4.3

Df 0.025

IPC-4101/21 /24 /26

UL - File Number E41625

Last Updated December 7, 2017
Revision No: 8

Product Features

Product Availability

Property		Typical Value	Units	Test Method
			Metric (English)	IPC-TM-650 (or as noted)
Pressed Thickness	A. 106	0.043 ±0.0008 (1.7 ±0.3)	mm (mil)	
	B. 1080	0.069 ±0.0008 (2.7 ±0.3)		
Resin Content	A. 106 B. 1080	65 ±1.5	%	
Resin Flow Testing	A. 106 B. 1080	R&R	—	2.3.17
Modified Circle Flow	A. 106 B. 1080	0.050-0.120	—	
Glass Transition Temperature (Tg) by DSC		170	°C	2.4.25C
Cure Temperature Recommended for Full Cure		370	°C	
Min. for Functional Bonding		325	°C	
Z-Axis CTE	Post-Tg	75	ppm/°C	2.4.24C
X/Y-Axis CTE	Pre-Tg	17/20	ppm/°C	2.4.24C
Thermal Conductivity		.30	W/mK	ASTM E1952
Thermal Stress 10 sec @ 288°C (550.4°F)	A. Unetched B. Etched	Pass	Pass Visual	2.4.13.1
Electric Strength (Laminate & laminated prepreg)		1750	kV/mm (V/mil)	2.5.6.2A
Peel Strength	Standard profile copper >>> After thermal stress	10.0	N/mm (lb/inch)	2.4.8C
Flammability (Laminate & laminated prepreg)		V-0	Rating	UL 94

The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.

